

## AMENDMENT TO THE CLAIMS

Claims 1-33. (cancelled)

Claim 34. (new) A piezoelectric generator, comprising:

a package substrate having an upper face and a lower surface;

a piezoelectric oscillator located on the upper face of said package substrate;

a lid member fixed to said package substrate in a manner such that it covers said piezoelectric oscillator;

an electric component mounted on the lower surface of said package substrate; and

a plurality of electrodes for external connection independently protruding from the lower surface of said package substrate;

wherein each of said electrodes for external connection are made of solder and have a height greater than the mounting height of said electronic component.

Claim 35. (new) The piezoelectric generator according to claim 34, wherein said package substrate is a multi-layer substrate.

Claim 36. (new) The piezoelectric generator according to claim 35, wherein said multi-layer substrate has a recess in which the piezoelectric oscillator is stored.

Claim 37. (new) The piezoelectric generator according to claim 34, wherein said package substrate comprises a flat plate.

Claim 38. (new) The piezoelectric generator according to claim 34, wherein a through hole for connecting the piezoelectric oscillator to a corresponding connecting terminal is formed in said package substrate in a region where the lid member is superposed on and bonded to the package substrate.

Claim 39. (new) The piezoelectric generator according to claim 34, wherein said package has a quadrangular shape, and said electrodes for external connection are arranged near the four corners of the package substrate, respectively, and said electronic component is arranged at the center of the package substrate.

Claim 40. (new) The piezoelectric generator according to claim 34, wherein each of said electrodes for external connection comprises a solder ball.

Claim 41. (new) The piezoelectric generator according to claim 40, wherein said solder ball includes an interior spacer.

Claim 42. (new) The piezoelectric generator according to claim 41, wherein said interior spacer is a copper ball.

Claim 43. (new) The piezoelectric generator according to claim 34, wherein said electronic component is an IC chip.

Claim 44. (new) The piezoelectric generator according to claim 34, wherein said electronic component comprises an IC chip and a capacitor.

Claim 45. (new) A piezoelectric generator apparatus comprising:

- a piezoelectric generator; and

- a mountable substrate on which the piezoelectric generator is mounted,

- wherein said piezoelectric generator includes:

  - a package substrate having an upper face and a lower surface;

  - a piezoelectric oscillator located on the upper face of said package substrate;

  - a lid member fixed to said package substrate in a manner such that it covers said piezoelectric oscillator;

  - an electronic component mounted on the lower surface of said package substrate;

- and

  - a plurality of electrodes for external connection made of solder and protruding from the lower surface of said package substrate, formed like respectively independent legs;

  - wherein said electronic component is housed in a space whose upper part, side parts and lower part are defined by the package substrate, the electrodes for external connection made of solder, and the mountable substrate, respectively.

Claim 46. (new) The mounting structure for a piezoelectric generator according to claim 45, wherein said electrodes for external connection comprise a solder ball.

Claim 47. (new) The mounting for a piezoelectric generator according to claim 46, wherein said solder ball includes an interior spacer.

Claim 48. (new) The mounting structure for a piezoelectric generator according to claim 47, wherein said spacer is a copper ball.

Claim 49. (new) The mounting structure for a piezoelectric generator according to claim 45, wherein said electronic component is an IC chip.

Claim 50. (new) The mounting structure for a piezoelectric generator according to claim 45, wherein said electronic component includes an IC chip and capacitor.

Claim 51. (new) A piezoelectric generator apparatus comprising:

- a piezoelectric generator, and

- a mountable substrate on which the piezoelectric generator is mounted,

- wherein said piezoelectric generator includes:

  - a package substrate;

  - a piezoelectric oscillator held on the side of the upper face of said package substrate;

  - a lid member fixed to said package substrate in a manner such that it covers said piezoelectric oscillator;

  - an electronic component mounted on the lower surface of said package substrate;

- and

a plurality of electrodes for external connection, protruding from the lower face of said package substrate, formed like respectively independent legs;

wherein said mountable substrate has a recess or through hole which allows at least a part of the electronic component to be stored when said piezoelectric generator is mounted on the mountable substrate.